

Summary (60 words)

The rapid growth of AI computing, advanced packaging, and higher power densities is driving the evolution from traditional board-level cooling to complete system-level thermal management. Cadence Cradle CFD enables engineers to accelerate thermal design by simplifying model preparation, improving simulation efficiency, and providing deeper insights into heat flow for faster and more confident engineering decisions.

Key Points

- AI & HPC increase thermal challenges.
- Advanced packaging demands system-level cooling.
- Transition from air cooling to liquid cooling.
- Reduce model preparation effort.
- Accelerate thermal simulation workflow.
- Gain better insights into heat flow and thermal bottlenecks.
- Optimize thermal performance before hardware prototyping.
- Faster design iterations and improved engineering productivity.